# Product End-of-Life Disassembly Instructions

**Product Category:** Desktops

**Marketing Name / Model**  
[List multiple models if applicable.]

- HP Pavilion Mini 300 Desktop and HP Stream Mini 200 Desktop

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td></td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>N/A</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>N/A</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>N/A</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>3</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>N/A</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>N/A</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing radioactive substances | 0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td></td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove bottom rubber then remove bottom screws *3.
2. Remove bottom case then remove HDD bracket.
3. Remove HDD and latched cable.
4. Remove system battery, DDR and WLAN module screw *1.
5. Remove SSD screw *1 if needed
6. Remove CPU fan screw *3 and remove thermal module screw *4.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
1. **Remove bottom screws**

1. Release bottom rubber by peeling off from the edge of it as shown in photo1

2. Release 3 bottom screws as shown in photo2 & 3 (M3*4L F W-ZN #2)

[Photo1]

[Photo2]

[Photo3]
2. Remove bottom case

1. Lift bottom case upwards by 2 hands
   (See Photo4)

2. Release 4 HDD bracket screws by turns 1/2/3/4
   (See Photo5)
   HDD bracket screws (M3*7 11L (K) W-ZN #2)
   (See Photo6)
3. Remove HDD

1. Move HDD bracket aside and pull the string to release cable from HDD  
   (See Photo7)

2. Release cable from M/B end  
   (See Photo8,9)
3. Release 4 screws from HDD bracket by turns
   (M3*4L P W-ZN #2).
   (See Photo10,11)

4. Take HDD out of bracket
   (See Photo12)
4. Remove system battery

1. Remove system battery from M/B  
   *(See Photo13)*

2. Remove battery connector from red circled header  
   *(See Photo14)*
5. Remove DDR, WLAN

1. Release DDR by pulling outwards of 2 hooks (See Photo15,16)
2. Release WLAN screw (M3*4L P W-ZN #2)  
(See Photo17,18)

Remove WLAN card and release ANT by ripping off the black tape  
(See Photo19,20)
6. Remove SSD (optional, if needed)

1. Release SSD screw (M3*4L P W-ZN #2)  
   (See Photo21,22)

   Remove SSD from M/B  
   (See Photo23)
7. Remove CPU fan, thermal module

1. Remove fan cable from M/B

2. Release 3 screws of fan module (TOP BLACK M3)

3. Release 4 screws from M/B (M5 M2*3L BLUE_W_ZN)
4. Remove thermal module from M/B